PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WOON CHUN KIM	02/12/2019
JUN HEYOUNG PARK	02/12/2019
JI HYE SHIM	02/12/2019
SUNG KEUN PARK	02/12/2019
GUN LEE	02/12/2019

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16291621

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	HOSANG LEE
SIGNATURE:	/Hosang Lee/
DATE SIGNED:	04/11/2019

Total Attachments: 3
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COMBINED DECLARATION (37 CFR 1.63) FOR U.S. PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT OF INVENTION

Title of Invention	**FAN-OUT SEMICONDUCTOR PACKAGE**

DECLARATION

As the below named and undersigned inventor, I hereby declare that:

This declaration is directed to:	X	The attached application, or
	☐	United States application or PCT international application number ____________________ filed on ____________________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: *A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56.*

ASSIGNMENT

WHEREAS, I have made an invention described and/or claimed in the above-identified application; and

WHEREAS, **SAMSUNG ELECTRO-MECHANICS CO., LTD**, a corporation of the Republic of Korea, having a place of business at **Maeyoung-Ro 150 (Maetan-Dong), Youngtong-Gu, Suwon-Si, Gyeonggi-Do, Republic of Korea** , (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title, and interest in and to said invention in all countries throughout the world and the above-identified United States patent application;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have assigned and do hereby assign to the ASSIGNEE, and its lawful successors and assigns, the entire right, title, and interest in and to said invention, the above-identified United States patent application and all divisions, continuations, and continuations-in-part of said application, and reissues, extensions, and renewals of Letters Patent granted thereon, and all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and all Letters Patents issuing on any such patent applications in the United States and foreign countries;

I hereby assign to the ASSIGNEE, and its lawful successors and assigns, the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Woon Chun KIM

Signature: Woon Chun Kim Date: Feb. 12th, 2019

NAME OF INVENTOR (Full Legal Name) : Jun Heyoung PARK

Signature: Jun Heyoung Park Date: Feb. 12th, 2019

NAME OF INVENTOR (Full Legal Name) : Ji Hye SHIM

Signature: Ji hye Shim Date: Feb. 12th, 2019

NAME OF INVENTOR (Full Legal Name) : Sung Keun PARK

Signature: sung keun park Date: Feb. 12th. 2019

NAME OF INVENTOR (Full Legal Name) : Gun LEE	
Signature:	Date: Feb. 12th. 2019